

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3832592

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JONG HYUN AHN	04/12/2016
WONHO LEE	04/12/2016
RECEIVING PARTY DATA	
Name:	INDUSTRY-ACADEMIC COOPERATION FOUNDATION
Street Address:	YONSEI UNIVERSITY, 50
Internal Address:	SEODAEMUN-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	03722
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15099198
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	215-979-1000
Email:	amherrman@duanemorris.com
Correspondent Name:	DUANE MORRIS LLP (PREV. BOCA RATON) IP D
Address Line 1:	30 SOUTH 17TH STREET
Address Line 4:	PHILADELPHIA, PENNSYLVANIA 19103-4196
ATTORNEY DOCKET NUMBER:	G1035-08101
NAME OF SUBMITTER:	GREGORY M. LEFKOWITZ
SIGNATURE:	/Gregory M. Lefkowitz/
DATE SIGNED:	04/15/2016
Total Attachments: 2	
source=G1035-08101_ASSIGNMENT#page1.tif	
source=G1035-08101_ASSIGNMENT#page2.tif	

ASSIGNMENT

WHEREAS, we, **Jong Hyun AHN** and **Wonho LEE** have invented certain new and useful improvements in and to the invention entitled:

*FLEXIBLE HIGH PERFORMANCE INORGANIC MATTER FET USING
BUILT-IN STRAIN OF INORGANIC MATTER ON INSULATOR WAFER*

described in an application for Letters Patent filed on April 14, 2016, and accorded U.S. Patent Application No. 15/099,198, which claims priority to South Korean Patent Application No. 10-2015-0053018, filed on April 15, 2015 (hereinafter collectively the "Invention").

AND, WHEREAS, **INDUSTRY-ACADEMIC COOPERATION FOUNDATION, YONSEI UNIVERSITY**, a South Korean university, having an address at Yonsei University, 50, Yonsei-ro, Seodaemun-gu, Seoul 03722, Republic of Korea (hereinafter "ASSIGNEE"), is desirous of acquiring certain rights in the Invention including all patents and patent applications thereto;

NOW, THEREFORE, in view of good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, we do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, our entire right, title and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto in and to said Invention including said United States patent application(s), any other United States patent application(s), including provisional, divisional, renewal, substitute, continuation, continuation-in-part, reexamination and reissue applications, and extensions thereof based in whole or in part on said United States patent application or in whole or in part on said Invention, any foreign applications, including international and regional applications, based in whole or in part on any of the aforesaid United States applications or in whole or in part on said Invention, in and to any and all letters patent, including extensions thereof, of any country which have been or may be granted on any of the aforesaid applications or on said Invention or any part(s) thereof, and in and to any right to claim priority to any of the aforesaid patents and/or patent applications;

AND we hereby authorize and request, Duane Morris LLP, whose address is 5100 Town Center Circle, Suite 650, Boca Raton, Florida 33486 to insert hereon any identification necessary or desirable for recordation of this document, including the filing date and application number of said application when known.


AND we hereby agree for ourselves and our heirs, executors and administrators to execute without further consideration any further documents and instruments which may be necessary, lawful and proper in the prosecution of said above-referenced application or in the preparation or prosecution of any continuing, substitute, divisional, renewal, reexamination or reissue application or in any amendments, extensions or interference proceedings, or other applications for patents of any region or country, that may be necessary to secure to ASSIGNEE its interest and title in and to said Invention or any part(s) thereof, and in and to said several patents or any of them;


AND we hereby covenant for ourselves and our legal representatives, and agree with said ASSIGNEE, its successors and assigns, that we have granted no right or license to make, use, sell or offer to sell said Invention, to anyone except said ASSIGNEE, that prior to the execution of this deed, my right, title and interest in said Invention had not been otherwise encumbered, and that we have not and will not execute any instrument in conflict therewith;

AND we do hereby authorize and request the United States Commissioner for Patents to issue any and all letters patent which may be granted upon said United States applications, or upon said Invention or any part(s) thereof when granted, to said ASSIGNEE;

IN WITNESS WHEREOF, we have hereunto set my hand and seal.

FOR ASSIGNOR: The Named Inventors

Date April 12th / 2016 Inventor 
Jong Hyun AHN

Date April 12th, 2016 Inventor 
Wonho LEE